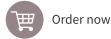


BAT17-04W

Series silicon RF Schottky diode pair









Product description

These Infineon RF Schottky diodes are silicon low barrier N-type devices with an integrated guard ring on-chip for overvoltage protection. Their low barrier height, small forward voltage and low junction capacitance, make BAT17-04W a suitable choice for mixer and detector applications at frequencies as high as 6 GHz.



Feature list

- Low inductance L_s = 1.4 nH (typical)
- Low capacitance C = 0.61 pF (typical) at frequency f = 1 MHz
- Industry standard SOT323-3 package (2.1 mm x 2 mm x 0.9 mm)
- Pb-free, RoHS compliant and halogen free

Product validation

Qualified for industrial applications according to the relevant tests of JEDEC47/20/22.

Potential applications

For mixers and detectors in:

- Wearables
- Smart metering
- Telematic systems
- Set top boxes

Device information

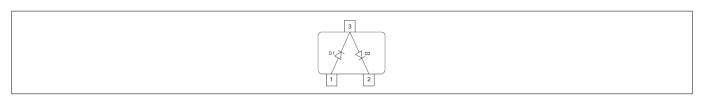


Table 1 Part information

Product name / Ordering code	Package	Pin configuration	Marking	Pieces / Reel
BAT17-04W / BAT1704WH6327XTSA1	SOT323-3	Series pair	54s	3 k

Attention: ESD (Electrostatic discharge) sensitive device, observe handling precautions!

BAT17-04W

Series silicon RF Schottky diode pair



Table of contents

Table of contents

	Product description	:
	Feature list	:
	Product validation	
	Potential applications	
	Device information	
	Table of contents	
1	Absolute maximum ratings	2
2	Electrical performance in test fixture	3
2.1	Electrical characteristics	
2.2	Characteristic curves	4
3	Thermal characteristics	6
4	Package information SOT323-3	8
	Revision history	
	Disclaimer	. 1(

1 Absolute maximum ratings

Table 2 Absolute maximum ratings at $T_A = 25$ °C, unless otherwise specified

Parameter	Symbol	Values		Unit	Note or test condition
		Min.	Max.		
Diode reverse voltage	V_{R}	_	4	V	
Forward current	I _F	_	130	mA	
Total power dissipation	P _{TOT}	_	150	mW	T _S ≤ 100 °C ¹⁾
Junction temperature	TJ	_	150	°C	
Operating temperature	T_{OP}	-55	125		
Storage temperature	T_{STG}	-55	150		

Attention: Stresses above the maximum values listed here may cause permanent damage to the device.

Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Exceeding only one of these values may cause irreversible damage to the component.

 $T_{\rm S}$ is the soldering point temperature.

Series silicon RF Schottky diode pair



Electrical performance in test fixture

Electrical performance in test fixture 2

Electrical characteristics 2.1

Electrical characteristics at T_A = 25 °C, unless otherwise specified Table 3

Parameter	Symbol	Values			Unit	Note or test condition
		Min.	Тур.	Max.		
Breakdown voltage	V_{BR}	4	_	-	V	/ _R = 10 μA
Reverse current	I_{R}	_	_	0.25	μΑ	V _R = 3 V
		_	_	1.25		$V_{\rm R} = 3 \text{ V}, T_{\rm A} = 60 ^{\circ}\text{C}^{1)}$
		_	_	10		V _R = 4 V
Forward voltage	V_{F}	0.2	0.27	0.35	V	/ _F = 0.1 mA
		0.25	0.34	0.45		/ _F = 1 mA
		0.35	0.42	0.60		/ _F = 10 mA
Forward voltage matching	ΔV _F	_	_	20	mV	I _F = 1 mA ²⁾
Differential forward resistance	R _F	_	8	15	Ω	I _F = 5 mA
Capacitance	С	0.4	0.61	0.7	pF	$V_{R} = 0 \text{ V}, f = 1 \text{ MHz}$
Inductance	L _S	_	1.4	_	nН	

3 Datasheet

2018-06-30

¹ Parameter is not subject to production test, min/max values are specified by design.

 $[\]Delta V_{\rm F}$ is the difference between lowest and highest $V_{\rm F}$ in a multiple diode component.



Electrical performance in test fixture

2.2 Characteristic curves

At T_A = 25 °C, unless otherwise specified

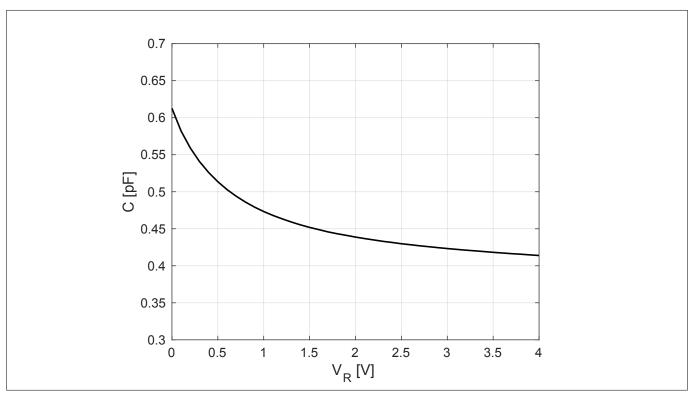


Figure 1 Capacitance C vs. reverse voltage V_R at frequency f = 1 MHz

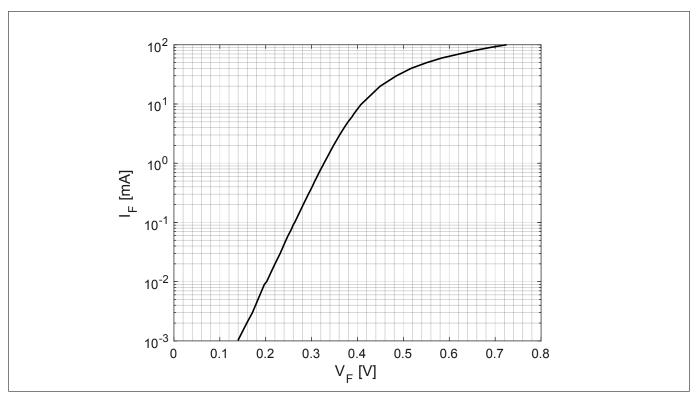


Figure 2 Forward current I_F vs. forward voltage V_F

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Electrical performance in test fixture

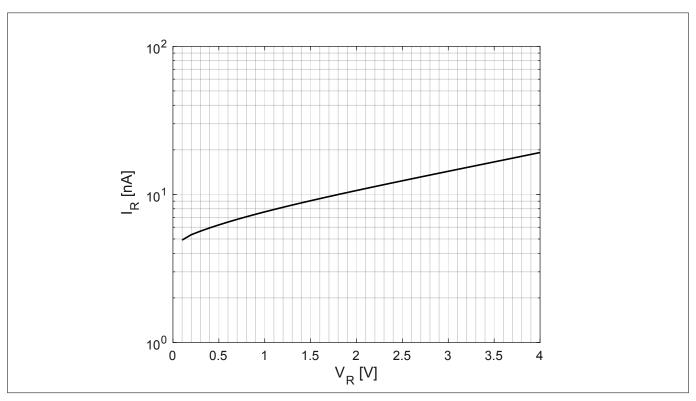


Figure 3 Reverse current I_R vs. reverse voltage V_R

Note: The curves shown in this chapter have been generated using typical devices but shall not be understood as a guarantee that all devices have identical characteristic curves.



2018-06-30

Thermal characteristics

3 Thermal characteristics

Table 4 Thermal resistance

Parameter	Sym	Values			Unit	Note or test condition
	bol	Min.	Тур.	Max.		
Thermal resistance	R _{thJS}	-	330	_	K/W	T _S = 100 °C 1)
(junction - soldering point)						

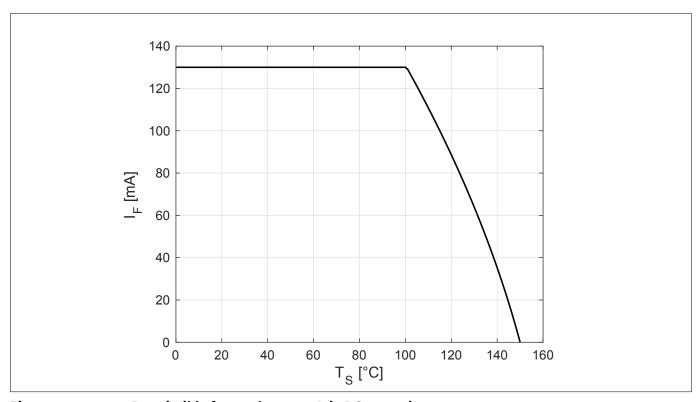


Figure 4 Permissible forward current I_F in DC operation

 $^{^{1}}$ For R_{thJS} in other conditions refer to the curves in this chapter.

Series silicon RF Schottky diode pair



Thermal characteristics

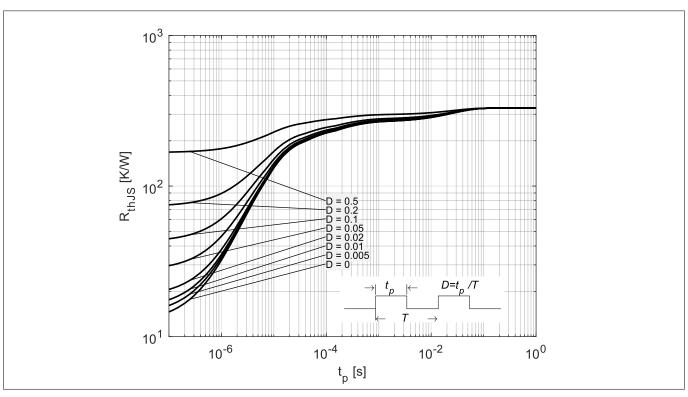
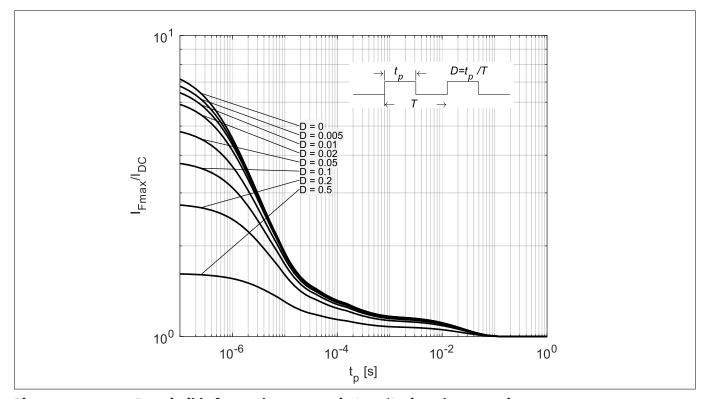


Figure 5 Thermal resistance R_{thJS} in pulse operation



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Figure 6 Permissible forward current ratio I_{Fmax}/I_{DC} in pulse operation

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Package information SOT323-3

4 Package information SOT323-3

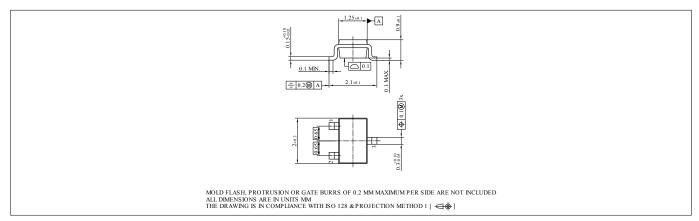


Figure 7 Package outline

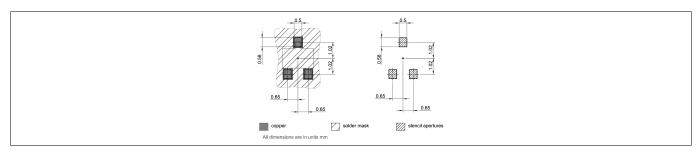


Figure 8 Foot print

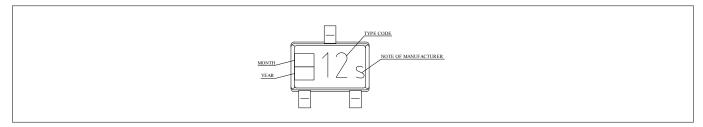


Figure 9 Marking layout example

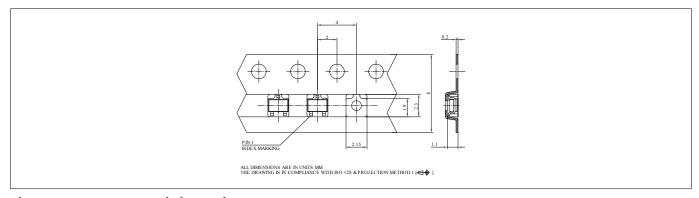


Figure 10 Tape information

BAT17-04W Series silicon RF Schottky diode pair



Revision history

Revision history

Document version	Date of release	Description of changes					Description of changes				
1.0	2018-09-07	 Change from series datasheet to individual one Initial release of datasheet Typical values and curves updated to the values of the production (No product or process change behind) Maximum values tightened (No product or process change behind) Typical curves removed 									

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